

DDR4 DIMM

TE Internal #: 2199155-3

DIMM Sockets, Double Data Rate (DDR) 4, Board-to-Bus Bar, 288
Position, Surface Mount, Vertical Module Orientation, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR4 DIMM SOCKETS



DRAM Type: **Double Data Rate (DDR) 4**
Connector System: **Board-to-Bus Bar**
Number of Positions: **288**
Termination Method to Printed Circuit Board: **Surface Mount**
Module Orientation: **Vertical**

[All DDR4 DIMM SOCKETS \(69\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 4
Connector System	Board-to-Bus Bar

Configuration Features

Number of Positions	288
Module Orientation	Vertical

Body Features

Ejector Type	Standard
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Contact Features

Contact Current Rating (Max)	.75 A
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Termination Features

Termination Method to Printed Circuit Board	Surface Mount
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Mechanical Attachment

Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	.85 mm[.033 in]
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Usage Conditions

Operating Temperature Range	-55 - 105 °C[-67 - 221 °F]
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Operation/Application

Circuit Application	Signal
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Packaging Features

Packaging Method	Hard Tray
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Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

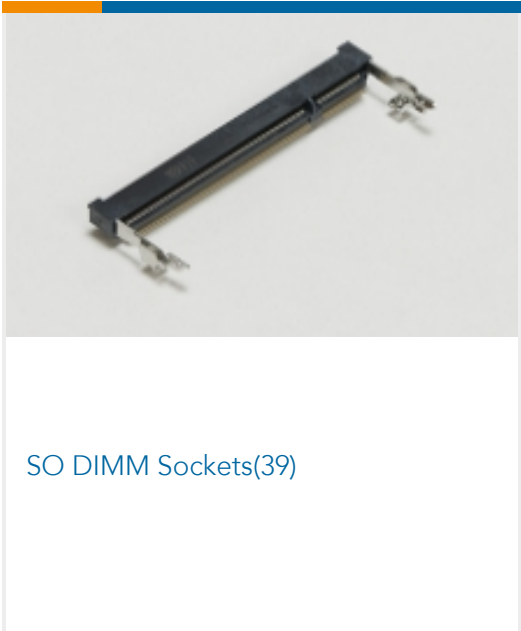
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

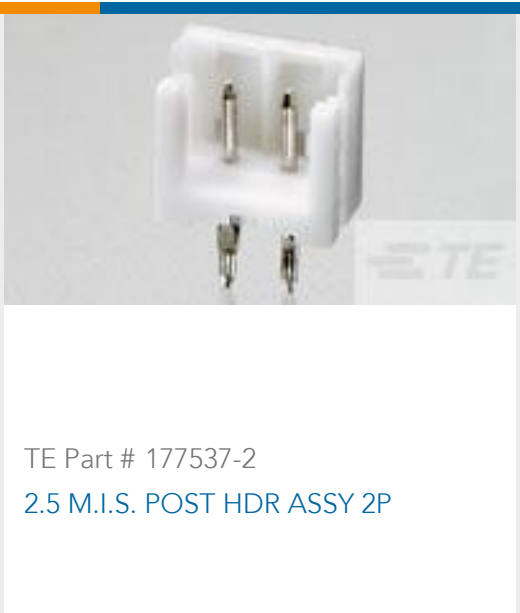


Also in the Series

DDR4 DIMM



Customers Also Bought



Documents

- CAD Files
- 3D PDF
- 3D
- Customer View Model
- ENG_CVM_CVM_2199155-3_D.2d_dxf.zip
- English



Customer View Model

[ENG_CVM_CVM_2199155-3_D.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2199155-3_D.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[DDR4 DIMM Socket Flyer \(English\)](#)

English

[DDR4 DIMM Socket Flyer \(Chinese\)](#)

Product Specifications

[Product Specification](#)

English